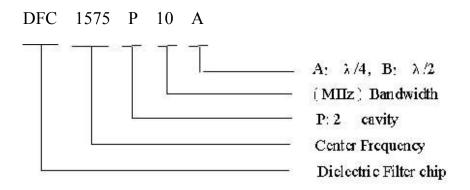
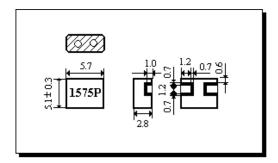
INTRODUTION

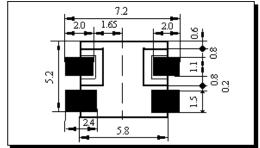
Microwave Dielectric Duplexer filter series are designed to be used in mobile & cordless phones with low insertion loss and high attenuation as well as chip design , which can simplify your complex tunning and circuit design .

Part Number



Dimension Unit mm





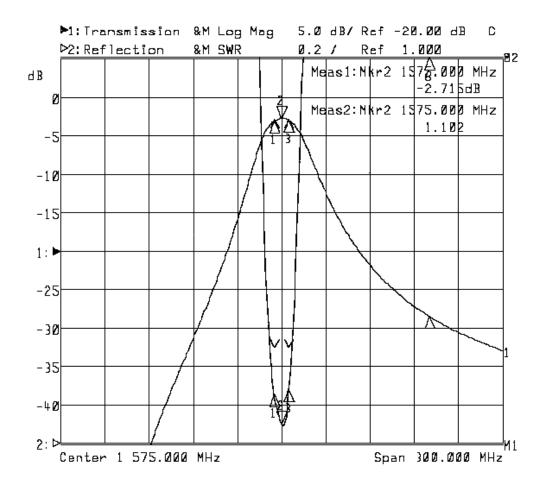
Structure and Material

NO	Part Name	Structure and material
4.1	Filter	Dielectric material
4.2	Number of pole	2pole
4.3	In/output Terminals	AgPlated
4.4	Ground Base	AgPlated

Electrical Characteristics

NO	Item	Specifications	PostEnvironmental Tolerance
5.1	Center frequency (fo)	1575.42-/+2.0 MHz	-/+2MHz
5.2	Insertion loss	3.0 dB	-/+0.5 dB
5.3	Band width	fo-/+5.0MHz	-/+0.5 MHz
5.4	Ripple (in BW)	0.5 dB Max.	-/+0.5 dB
5.5	V.S.W.R (in BW)	1.5 Max.	-/+0.5
5.6	Attenuation (Absolute value)	25 (fo + 100MHz) 40 (fo - 100MHz)	-/+2 dB
5.7	Permissible Input power (Max)	1 Watt	
5.8	In/output impedance	50	

• Characteristic curve



Environmental specifications

Post Environmental Tolerance (Refer to the table 2)

Temperature range 25–/+3 °C

Relative Humidity range 55~75%RH

Operating Temperature range $-10 \,^{\circ}\text{C} \sim +70 \,^{\circ}\text{C}$

Storage Temperature range -25 °C ~+85 °C

Moisture Proof

The device should satisfy the electrical characteristics specified in paragraph 5.1~5.6 after exposed to the temperature 40–/+2 °C and the relative humidity 90~95% RH for 96 hours and 1~2 hours recovery time under normal condition.

Vibration Resist

The device should satisfy the electrical characteristics specified in paragraph $5.1\sim5.6$ after applied to the vibration of 10 to 55Hz with amplitude of 1.5mm for 2 hours each in X, Y and Z directions.

Drop Shock

The device should satisfy the electrical characteristics specified in paragraph 5.1~5.6 after dropping onto the hard wooden board from the height of 30cm for 3 times each facet of the 3 dimensions of the device.

High Temperature Endurance

The device should satisfy the electrical characteristics specified in paragraph 5.1~5.6 after exposed to temperature 80–/+5 °C for 24–/+2 hours and 1~2 hours recovery time under normal temperature.

Low Temperature Endurance

The device should also satisfy the electrical characteristics specified in paragraph 5.1~5.6 after exposed to the temperature -25 °C-/+3 °C for 24-/+2 hours and to 2 hours recovery time under normal temperature.

Temperature Cycle Test

The device should also satisfy the electrical characteractics specified in paragraph 5.1~5.6 after exposed to the low temperature -25 °C and high temperature +85 °C for 30-/+2 min each by 5 cycles and 1 to 2 hours recovery time under normal temperature.

Solder Heat Proof

The device should be satisfied after preheating at $120\,^{\circ}\text{C} \sim 150\,^{\circ}\text{C}$ for 60 seconds and dipping in soldering Sn at $260\,^{\circ}\text{C} + 10\,^{\circ}\text{C}$ for 10--/+0.5 seconds.

• Tensile Strength of Terminal

The device should not be broken after tensile force of 1.0kg is slowly applied to pull a lead pin of the fixed device in the lead axis direction for 10-/+1 seconds.

Bending Resist Test

Weld the product to the center part of the PCB with the thickness 1.6–/+0.2mm as the illustration shows, and keep exerting force arrow-ward on it at speed of:

1mm/S, and hold for 5-/+1S at the position of 2mm bending distance, so far, any peeling off of the product metal coating should not be detected.

